

Appl. No. 10/702,442
Amendment dated: August 15, 2006
Reply to OA of: May 15, 2006

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1(currently amended). A method of treating a surface of a substrate, said method comprising the following steps of:

(a) forming bubbles with a liquid and a gas on the surface of the substrate comprising immersing a plurality of the substrates which are equidistantly arranged and are parallel to one another in the liquid contained in a bath such that only bottom portions of the substrates are immersed in the liquid, and the gas is introduced to the bath to form the bubbles; and

(b) allowing the gas bubbles to ascend along the surface of the substrate, including the surface above the horizon of the liquid, such that the gas bubbles work to strip a substance from the surface of the substrate, or that the gas bubbles work to form a substance on the surface of the substrate;

wherein the liquid comprises ozone water, the gas comprises a gas mixture comprising ozone, and the substance comprises a photoresist.

2(original). The method as defined in claim 1, wherein the gas bubbles work to strip a substance from the surface of the substrate in the step (b).

3(currently amended). The method as defined in claim 2, wherein the substrate is a wafer; ~~wherein the substance is a photoresist or an organic containment on the surface of the water.~~

Claim 4(canceled).

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5(previously presented). The method as defined in claim 1, wherein the substrate is vertically immersed in the liquid contained in the bath, and the substrate is driven to turn in the bath, thereby enabling outer edges of the substrate to be immersed in the liquid in rotation.

Claim 6-9(canceled).